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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10056350	FILING DATE 01/24/2002	CLASS 257	SUBCLASS G69	GAU 2825	EXAMINER Y. YEVSIXOL
**APPLICANTS: Cobbley Chad;					
<p>**CONTINUING DATA VERIFIED:</p> <p>THIS APPLICATION IS A DIV OF 09/060,740 04/15/1998 <i>ABN</i> <i>YES V4</i> <i>USP</i> <i>6,501,57</i></p>					
<p>** FOREIGN APPLICATIONS VERIFIED: <i>NO V4</i></p>					
PG-PUB DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met		<input type="checkbox"/> yes <input checked="" type="checkbox"/> no		ATTORNEY DOCKET NO	
Verified and Acknowledged Examiners's initials		<i>Y. YEVSIXOL V4</i>		11675.143.2	
TITLE : Process for providing electrical connection between a semiconductor die and a semiconductor die receiving member					
U.S. DEPT. OF COMM. PAT. & TM. FTD 4361 (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		Assistant Examiner		CLAIMS ALLOWED	
ISSUE FEE				Total Claims	Print Claim for 0.0
Amount Due	Date Paid	Primary Examiner		DRAWING	
				Sheets Drawn	Figures Drawn
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE		Application Examiner	
		<p>WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.</p>			

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